

FL2026M
No Clean Liquid Flux

Product Description

Hasaconi FL2026M is a RMA liquid flux that has excellent oxide removal capabilities and is able to reduce the surface tension of lead free solder to minimise solder shorts during the assembly process. The good solderability result is highly consistent and repeatable. Although FL2026M has high solid content, it has been formulated for use in both foaming and spraying applications as it is able to form uniform bubble size in the foaming process and does not clog the spray nozzle after prolonged usage.

Application

FL2026M is specially formulated for both foaming and spraying process. On board pre-heat temperature is recommended to be 80 – 100 °C. It can also be used in the dipping applications.

Residue Removal

Since the residues are minimal and non-corrosive, removal is usually not required. If cleaning is required, the flux residue could be removed by any solvent or aqueous flux cleaner available in the market.

Recommended Solvent

Asahi's complementary Solvent S2012M. Solvent can be stored for about 2 years under normal storage conditions of 25°C.

Health and Safety

Observe standard precautions for handling and use, such as well-ventilated areas and avoidance of prolonged or repeated contact with the skin. For more information, please refer to the Material Safety Data Sheet.

Storage

Under proper storage condition, FL2026M can be stored for up to 6 months. FL2026M is flammable. Keep away from all sources of heat, sparks, flame and sunlight.

Packaging

Available in 18kg/carboy.

Specification

Item	Result
State	Liquid
Colour	Light brown
Specific Gravity @ 25°C	0.840 +/- 0.005
JIS Z 3197 8.2.2	
Non-volatile Solid Content (110°C, 1hr)	24.0 +/- 1.0 wt%
IPC-TM-650 2.3.34	
JIS Z 3197 8.1.3	
Halide Content	0.08 +/- 0.01 wt%
JIS Z 3197 8.1.4.2.1	
Acid Value Test	51.0 +/- 2.0 mg KOH/g flux
IPC-TM-650 2.3.13	
JIS Z 3197 8.1.4.1	
Water Extract Resistivity	> 1 x 10 ⁴ Ω-cm
JIS Z 3197 8.1.1	
Surface Insulation Resistance (85°C, 85%RH, 168hrs)	> 1 x 10 ⁸ Ω, Pass
IPC-TM-650 2.6.3.3	
JIS Z 3197 8.5.3	> 1 x 10 ¹¹ Ω, Pass
Electromigration (85°C, 88.5%RH, 596hrs)	Pass
IPC-TM-650 2.6.14.1	
Copper Corrosion Test	Pass
IPC-TM-650 2.6.15	
JIS Z 3197 8.4.1	
Copper Mirror Test	Classified as "M", Pass
IPC-TM-650 2.3.32	
JIS Z 3197 8.4.2	
Flux Activity Classification	ROM1
IPC J-STD-004	
Spread Factor	> 75% (SnCu) > 90% (SnPb)
JIS Z 3197 8.3.1.1	
Residue Dryness Test	Dry
IPC-TM-650 2.4.47	
JIS Z 3197 8.5.1	
Surface Finish	Matte

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